

# Xilinx to Deliver Talks at SEMICON China 2012

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*Xilinx Vice President Sandeep Bharathi to highlight 2.5-D IC case study, high bandwidth IC design challenges & opportunities in two technology forums on March 21 & 22*

Xilinx has announced its participation at [SEMICON China 2012](#) [1] taking place in Shanghai, China from March 20 through 22.

**What:** SEMICON China 2012

**Where:** Shanghai New International Expo Centre, Shanghai, China

**When:** March 20 - 22, 2012

Xilinx vice president of engineering, Sandeep Bharathi, will join semiconductor industry leaders from around the world in two full-day events on March 21 and 22, respectively: the [3D-IC Technology Forum](#) [2] and [China Market: IC from Design to Manufacturing](#) [3].

Bharathi manages FPGA digital design development at Xilinx, including CAD and FPGA product tape outs, affording him unique insights into advanced chip design and manufacturing challenges and opportunities at 28nm, and in 3-D IC integration and packaging.

The 3-D IC forum will focus on breakthrough 3-D IC integration and packaging technologies being pioneered by today's semiconductor companies to achieve ~more than Moore in response to end market demand for higher performance, lower power, smaller form factor, lower cost electronic products.

The China IC from design to manufacturing forum will convene prestigious scholars and experts to discuss the growing role of the local IC industry in the broader global semiconductor market, and to share advanced engineering and scientific information, ideas and solutions for the future. The communications sector will be a key area of emphasis for speakers, including: *Current IC Manufacturing Technology for Telecommunications, 4G System Architecture, and IC Design in 4G Systems*.

### **3-D-IC Technology Forum**

**Wednesday, March 21**

**2:00-2:30 p.m., Kerry Hotel Pudong, Shanghai (Shangri-La Group), Pudong Ballroom 4**

#### ***2.5-D ICs: Just a Stepping Stone or a Long Term Alternative to 3-D?***

Bharathi's talk will cover the progression of 3-D IC technology, challenges of 3-D vs. 2.5-D IC design and manufacturing, highlights from a 2.5-D FPGA case study, and future directions for the industry.

### **The China Market: IC from Design to Manufacturing**

**Thursday, March 22**

**3:00 - 3:30 p.m., Kerry Hotel Pudong, Shanghai (Shangri-La Group),  
Function Room 4**

#### ***High Bandwidth IC Design Challenges & Solutions***

Bharathi will also deliver a session talk on the challenges facing the communications industry to keep up with the insatiable demand for bandwidth, and how the latest innovations in programmable devices and associated design tools and IP are delivering unprecedented levels of performance while reducing design time.

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#### **Links:**

[1] <http://www.semiconchina.org/>

[2] [http://www.semiconchina.org/article\\_2337\\_799.htm](http://www.semiconchina.org/article_2337_799.htm)

[3] [http://www.semiconchina.org/article\\_2338\\_803.htm](http://www.semiconchina.org/article_2338_803.htm)